L Number	Hits	Search Text	DB	Time stamp
1	3	(semiconductor adj substrate) and (glass adj substrate) and ((conductive adj plug) with insulat$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:06
3	18	((conductive adj plug) with insulat$) and imaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:11
4	1	((conductive adj plug) with insulat$) and imager	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:11
5	77	((conductive adj plug) with insulat$) and optical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:17
6	19	((conductive adj plug) with oxide) and optical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:17
7	6	((conductive adj plug) with oxide) and imaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:18
8	2	((conductive adj plug) with oxide) and imager	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:18
9	152	((conductive adj material) with oxide) and imager	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:19
10	0	((conductive adj material) with oxide with (through adj hole)) and imager	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:19
11	0	((conductive adj material) with oxide with (hole)) and imager	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:19
12	3	((conductive adj material) with oxide with (via)) and imager	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:20
13	9	((conductive adj material) with oxide with (via)) and imaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:20
14	30	((conductive adj material) with oxide with (via)) and optical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:51
16	10	(imaging adj device) and (reinforce$ near plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:54

17	26	(imaging adj device) and (reinforce$ near (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:58
19	15	(imaging adj device) with reinforce$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/18 09:58
-	6	(solid adj state adj imaging adj device) and translucent and (through adj hole) and terminal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:07
-	17	(imaging adj device) and translucent and (through adj hole) and terminal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 13:13
-	106	(imaging adj device) and translucent and (via) and terminal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 13:20
-	59	(imaging adj device) and translucent and (hole) and terminal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:30
-	6	(solid adj state adj imaging adj device) and translucent and (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:06
-	725	(solid adj state adj imaging adj device) and (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 13:25
-	18	(solid adj state adj imaging adj device) and (semiconductor adj substrate) and (external adj terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 15:54
-	20	(solid adj state adj imaging adj device) and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:09
-	92	(imaging adj device) and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:11
-	1	(imaging adj device) and ((hole or via or plug) adj semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:12
-	0	(imaging adj device) and ((hole or via or plug) adj semiconductor adj substrate) and (transparent adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:13
-	1	(imaging adj device) and ((hole or via or plug) adj semiconductor adj substrate) and (translucent adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:13

-	2	(imaging adj device) and ((hole or via or plug) near (semiconductor adj substrate)) and (translucent adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:13
-	5	(imaging adj device) and ((hole or via or plug) near (substrate)) and (translucent adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:14
-	6	(imaging adj device) and ((hole or via or plug) with (substrate)) and (translucent adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:18
-	295	257/89.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:37
-	1600	257/59.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:04
-	109	257/59.ccls. and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:39
-	1498	257/72.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:51
-	121	257/72.ccls. and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 17:55
-	595	257/434.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:04
-	6	257/434.ccls. and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:06
-	93	257/460.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:18
-	3	257/460.ccls. and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:06
-	465	257/462.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:08
-	2	257/462.ccls. and (semiconductor adj substrate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 18:41

–	1385	(semiconductor adj substrate) and (glass adj substrate) and display and image	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:11
–	663	through adj hole adj formed adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 06:37
–	45	through adj hole adj formed adj semiconductor adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:12
–	250	348/340.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:18
–	0	translucent adj member adj formed adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:31
–	1	transparent adj member adj formed adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:32
–	268	transparent near (formed adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:32
–	5	translucent near (formed adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:33
–	628	glass near (formed adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/27 19:33
–	87	(through adj hole adj formed adj substrate) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 06:57
–	256	(hole adj formed adj substrate) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 06:59
–	162	438/75.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 07:04
–	728	438/73.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 07:08
–	210	438/73.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 07:21

-	17	257/252.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 07:34
-	32	257/253.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 07:37
-	101	257/414.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 07:43
-	1252	257/$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj substrate) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 08:39
-	28	257/$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj member) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 08:46
-	19	438/$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj member) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 08:50
-	6	348/$.ccls. and (semiconductor adj substrate) and .((glass or transparent or translucent) adj member) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:11
-	4	((glass or transparent or translucent) adj member) near (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:13
-	560	((glass or transparent or translucent)_ near (semiconductor adj substrate)) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 09:15
-	1039	(solid adj state adj imaging adj device) and (translucent or glass or transparent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:38
-	125	(solid adj state adj imaging adj device) and (quartz)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/28 10:39
-	0	351997.FREF.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:55
-	0	0351997.FREF.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:55
-	1	2001351997.FREF.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:57

-	0	2001351997.FRPD.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:56
-	0	351997.FRPD.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:56
-	1	173845.FREF.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:57
-	0	2000173845.FREF.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 08:57
-	1	173845.FRPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:05
-	0	fumio-hata.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:08
-	0	fumi-hat$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:08
-	0	fumi-ha$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:08
-	0	fumi-h$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:08
-	10	fumio-h$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:09
-	0	fumio-hata.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:10
-	1	fumio-hat$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/30 09:10
-	30	(reinforcement adj plate) and (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:03
-	1	(reinforcement adj plate) and (solid adj state adj imaging adj device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:04

-	5	(reinforcement adj plate) and (imaging adj device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:11
-	57	(sio or (silicon adj oxide)) and (imaging adj device) and (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:37
-	161	(sio or (silicon adj oxide)) and (optical adj element) and (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:38
-	49	((sio or (silicon adj oxide)) with via) and (optical adj element)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:34
-	35	((sio or (silicon adj oxide)) with via) and (imaging adj device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:34
-	55	(sio or (silicon adj oxide)) and (imaging adj device) and (through adj hole) and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:38
-	23	((sio or (silicon adj oxide)) with thickness) and (optical adj element) and (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/16 18:38